

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2742177

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>YU-HSIANG HU</td> <td>02/18/2014</td> </tr> <tr> <td>WEI-YU CHEN</td> <td>02/18/2014</td> </tr> <tr> <td>MING-DA CHENG</td> <td>02/18/2014</td> </tr> <tr> <td>HUNG-JUI KUO</td> <td>02/18/2014</td> </tr> <tr> <td>CHUNG-SHI LIU</td> <td>02/18/2014</td> </tr> </tbody> </table>		Name	Execution Date	YU-HSIANG HU	02/18/2014	WEI-YU CHEN	02/18/2014	MING-DA CHENG	02/18/2014	HUNG-JUI KUO	02/18/2014	CHUNG-SHI LIU	02/18/2014
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CHUNG-SHI LIU	02/18/2014												
RECEIVING PARTY DATA													
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.												
Street Address:	NO. 8, LI-HSIN RD. 6												
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK												
City:	HSIN-CHU												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14189701</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14189701								
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Application Number:	14189701												
CORRESPONDENCE DATA													
Fax Number:	(972)732-9218												
Phone:	972-732-1001												
Email:	docketing@slater-matsil.com												
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
Correspondent Name:	SLATER & MATSIL, L.L.P.												
Address Line 1:	17950 PRESTON ROAD, SUITE 1000												
Address Line 4:	DALLAS, TEXAS 75252												
ATTORNEY DOCKET NUMBER:	TSM13-1894												
NAME OF SUBMITTER:	WENDY SAXBY												

PATENT

Signature:	/Wendy Saxby/
Date:	02/25/2014
Total Attachments: 2 source=44H5864#page1.tif source=44H5864#page2.tif	

ATTORNEY DOCKET NO. TSM13-1894

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

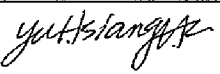
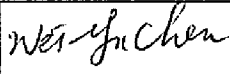
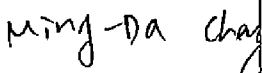
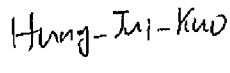
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of TW, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu 300-77, TW, is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	PACKAGES WITH SOLDER BALL REVEALED THROUGH LASER			
SIGNATURE OF INVENTOR AND NAME	 Yu-Hsiang (James) Hu	 Wei-Yu Chen	 Ming-Da Cheng	 Hung-Jui Kuo
DATE	2014.02.18	2014.02.18	2014.2/18	2014.02.18 Hung
RESIDENCE	Hsin-Chu, Taiwan	Taipei City, Taiwan	Jhubei City, Taiwan	Hsin-Chu, Taiwan

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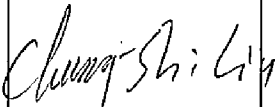
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NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

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IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	PACKAGES WITH SOLDER BALL REVEALED THROUGH LASER			
SIGNATURE OF INVENTOR AND NAME	 Chung-Shi Liu			
DATE	2/18/2014			
RESIDENCE	Hsin-Chu, Taiwan			